

PCN Number:	20230629002.1	PCN Date:	June 30, 2023																		
Title:	Qualification of new Fab site (FFAB) using qualified Process Technology, Die Revision and additional Assembly BOM options for select devices																				
Customer Contact:	Change Management team	Dept:	Quality Services																		
Proposed 1st Ship Date:	Sep 29, 2023	Estimated Sample Availability:	Jul 29, 2023																		
*Sample requests received after July 29, 2023 will not be supported.																					
Change Type:																					
<input type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material																			
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process																			
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/> Wafer Fab Site																			
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/> Wafer Fab Materials																			
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/> Wafer Fab Process																			
PCN Details																					
Description of Change:																					
Texas Instruments is pleased to announce the qualification of a new fab & process technology (FFAB, BICOM3XHV) and assembly BOM options (MLA) for selected devices as listed below in the product affected section.																					
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>SFAB</td> <td>JIBB</td> <td>150 mm</td> <td>FFAB</td> <td>BICOM3XHV</td> <td>200 mm</td> </tr> </tbody> </table>			Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	SFAB	JIBB	150 mm	FFAB	BICOM3XHV	200 mm	
Current Fab Site			Additional Fab Site																		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																
SFAB	JIBB	150 mm	FFAB	BICOM3XHV	200 mm																
The die was also changed as a result of the process change.																					
Assembly BOM options are noted below:																					
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>Additional</th> </tr> </thead> <tbody> <tr> <td>Wire Type</td> <td>1.15 mil Au</td> <td>1.0 mil Cu</td> </tr> <tr> <td>Mount compound</td> <td>4205846</td> <td>4147858</td> </tr> <tr> <td>Mold compound</td> <td>4209640</td> <td>4226323</td> </tr> </tbody> </table>				Current	Additional	Wire Type	1.15 mil Au	1.0 mil Cu	Mount compound	4205846	4147858	Mold compound	4209640	4226323							
	Current	Additional																			
Wire Type	1.15 mil Au	1.0 mil Cu																			
Mount compound	4205846	4147858																			
Mold compound	4209640	4226323																			
Qual details are provided in the Qual Data Section.																					
Reason for Change:																					
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.																					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																					
None																					
Impact on Environmental Ratings:																					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																					
<table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>				RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change										
RoHS	REACH	Green Status	IEC 62474																		
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Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
FR-BIP-1	TID	DEU	Freising

Die Rev:

Current

New

Die Rev [2P]	Die Rev [2P]
A	A

Sample product shipping label (not actual product label)

 **TEXAS INSTRUMENTS**
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 / 260C / 1 YEAR SEAL DT
 MSL 1 / 235C / UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) ~~CSO: SHE~~ (21L) ~~CCO: USA~~
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

XTR115U/2K5	XTR115UA/2K5	XTR116U/2K5	XTR116UA/2K5
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For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: XTR115U	QBS Process Reference: OPA1637DGKT	QBS Package Reference: INA849DR
HAST	A2	Biased HAST	130C	96 Hours	-	3/231/0	-
HAST	A2	Temperature Humidity Bias	85C/85%RH	1000 Hours	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C	96 Hours	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65/150C	750 Cycles	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0
HTOL	B1	Life Test	100C	300 Hours	-	-	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	3/9/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	3/9/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/6/0	3/18/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	1/30/0

- QBS: Qual By Similarity

- Qual Device XTR115U is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: XTR116UA	QBS Process Reference: OPA1637DGKT	QBS Product Reference: XTR115U	QBS Package Reference: INA849DR
HAST	A2	Biased HAST	130C	96 Hours	-	3/231/0	-	-
HAST	A2	Temperature Humidity Bias	85C/85%RH	1000 Hours	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C	96 Hours	-	3/231/0	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
TC	A4	Temperature Cycle	-65/150C	750 Cycles	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	3/231/0
HTOL	B1	Life Test	100C ^A	300 Hours	-	-	-	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	3/9/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	3/9/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	3/18/0	1/3/0	1/6/0
CHAR	E5	Electrical Characterization	Per datasheet specifications	-	1/30/0	3/90/0	1/30/0	1/30/0

- QBS: Qual By Similarity
- Qual Device XTR116UA is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

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Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

^A T_j =150C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: XTR115U Die rev AB	QBS Package Reference: INA848ID	QBS Process Reference: OPA1637DGKT	QBS Product Reference: XTR115U Die rev AA	QBS Package Reference: INA849DR
HAST	A2	Biased HAST	130C	96 Hours	-	-	3/231/0	-	-
HAST	A2	Temperature Humidity Bias	85C/85%RH	1000 Hours	-	3/231/0	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	3/231/0
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	3/231/0	3/231/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	-	3/231/0
HTOL	B1	Life Test	100C ¹	300 Hours	-	3/231/0	-	-	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	3/9/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	3/9/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	3/18/0	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	2/60/0	3/90/0	-	1/30/0

- QBS: Qual By Similarity
- Qual Device XTR115U/2K5 is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2209-050

¹ T_J of device at 150C

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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